

# SOT966-1

plastic low profile fine-pitch ball grid array package; 208 balls; body 12 x 12 x 1 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LFBGA208
<b>Package type industry code</b>	LFBGA208
<b>Package style descriptive code</b>	LFBGA (low profile fine-pitch ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	22-8-2006

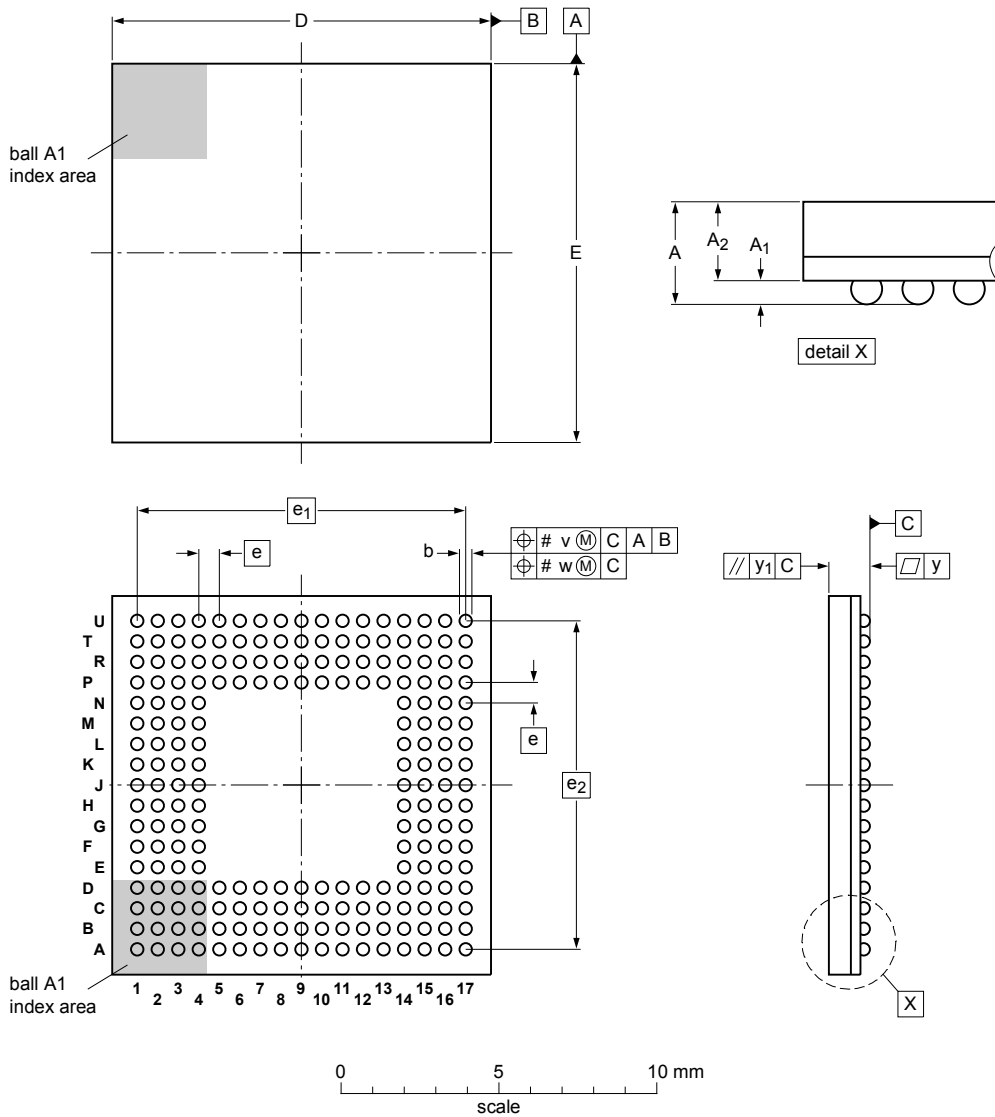
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	11.9	-	12	12.1	mm
E	package width	11.9	-	12	12.1	mm
A	seated height	[tbd]	-	1.45	1.45	mm
A <sub>2</sub>	package height	0.95	-	1	1.1	mm
n <sub>2</sub>	actual quantity of termination	-	-	208	-	



## 2. Package outline

LFBGA208: plastic low profile fine-pitch ball grid array package; 208 balls; body 12 x 12 x 1 mm SOT966-1



**DIMENSIONS** (mm are the original dimensions)

UNIT	A <sub>max</sub>	A <sub>1</sub>	A <sub>2</sub>	b	D	E	e	e <sub>1</sub>	e <sub>2</sub>	v	w	y	y <sub>1</sub>
mm	1.45	0.35 0.25	1.10 0.95	0.45 0.35	12.1 11.9	12.1 11.9	0.65	10.4	10.4	0.15	0.08	0.1	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT966-1						06-08-08 06-08-22

Fig. 1. Package outline LFBGA208 (SOT966-1)

### 3. Legal information

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